

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC080N12LS G	**Issued**	15. May 2021
MA#	MA004819020		
Package	PG-TDSON-8-39	**Weight***	119.76 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.857	1.55	1.55	15510	15510
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		316	
	non noble metal	copper	7440-50-8	37.762	31.54	31.58	315317	315728
wire	noble metal	gold	7440-57-5	0.043	0.04	0.04	363	363
encapsulation	organic material	carbon black	1333-86-4	0.084	0.07		705	
	plastics	epoxy resin	-	6.673	5.57		55717	
	inorganic material	silicondioxide	60676-86-0	35.474	29.62	35.26	296219	352641
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12122	12122
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1382	1382
solder	non noble metal	tin	7440-31-5	0.051	0.04		424	
	noble metal	silver	7440-22-4	0.064	0.05		531	
	non noble metal	lead	7439-92-1	2.427	2.03	2.12	20270	21225
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		186	
	non noble metal	copper	7440-50-8	22.292	18.61	18.64	186139	186381
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.45	9.46	94525	94648
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com